

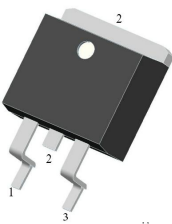
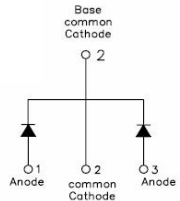
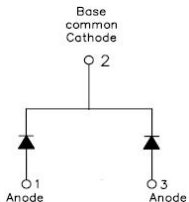
ST30120C/STB30120C SCHOTTKY RECTIFIER

Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features

- 150 °C T_J operation
- Center tap configuration
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

ST30120C 	STB30120C 
	
TO-220AB	D ² PAK

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V _{RRM}	-	120	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _R			
Average Rectified Forward Current	I _{F (AV)}	50% duty cycle @T _c =110°C, rectangular wave form	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse	200	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	V_{F1}	@ 5A, Pulse, $T_J = 25^{\circ}\text{C}$	0.51	-	V
		@ 7.5A, Pulse, $T_J = 25^{\circ}\text{C}$	0.58	-	
		@ 15A, Pulse, $T_J = 25^{\circ}\text{C}$	0.76	0.97	
	V_{F2}	@ 5A, Pulse, $T_J = 25^{\circ}\text{C}$	0.46	-	V
		@ 7.5A, Pulse, $T_J = 125^{\circ}\text{C}$	0.52	-	
		@ 15A, Pulse, $T_J = 125^{\circ}\text{C}$	0.64	0.76	
Reverse Current(Per Leg)*	I_{R1}	@ $V_R = \text{rated } V_R, T_J = 25^{\circ}\text{C}$	0.03	0.8	mA
	I_{R2}	@ $V_R = \text{rated } V_R, T_J = 125^{\circ}\text{C}$	6	50	mA
Junction Capacitance	C_T	@ $V_R = 5\text{V}, T_C = 25^{\circ}\text{C}$ $f_{\text{SIG}} = 1\text{MHz}$	600	-	pF

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case(Per Leg)	$R_{\theta\text{JC}}$	DC operation	2.2	$^{\circ}\text{C/W}$

Ratings and Characteristics Curves

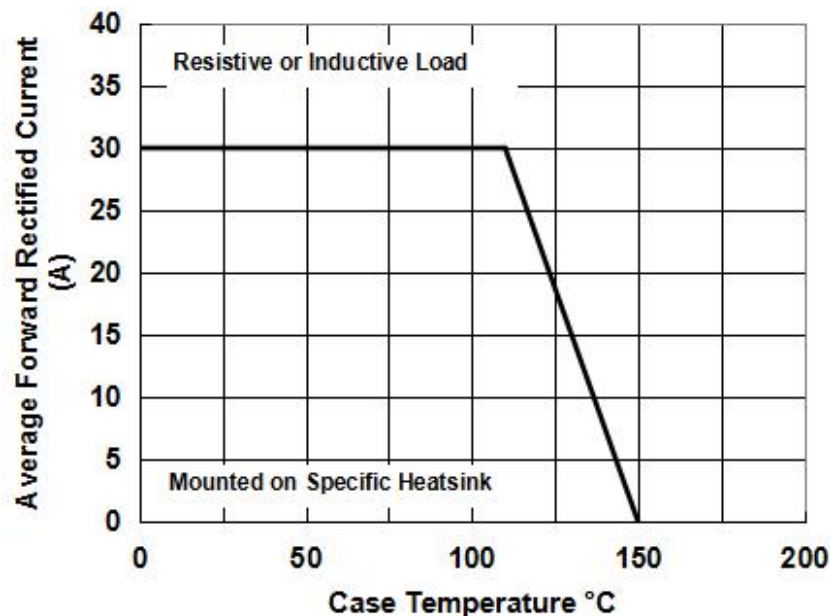


Figure 1. Maximum Forward Current Derating Curve

Figure 2
Typical Forward Characteristics

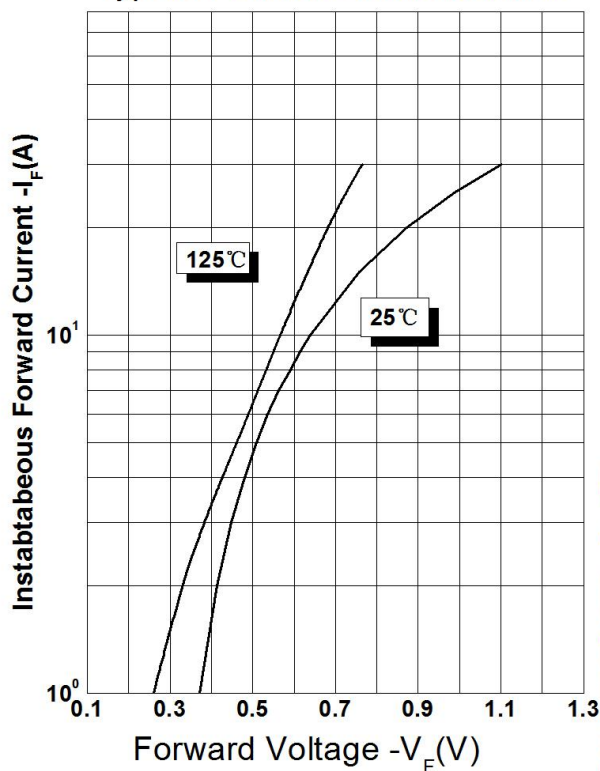


Figure 3
Typical Reverse Characteristics

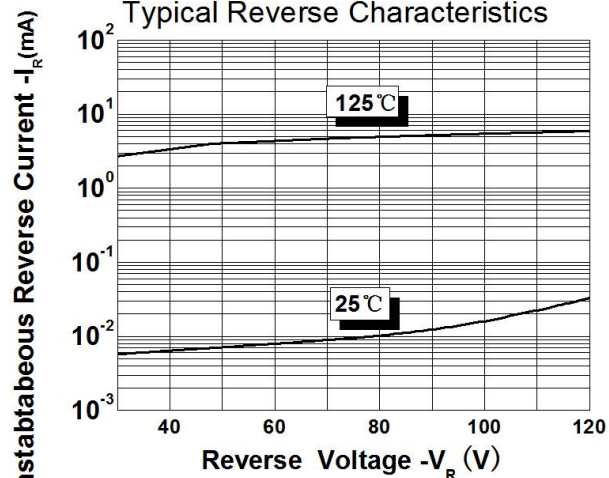
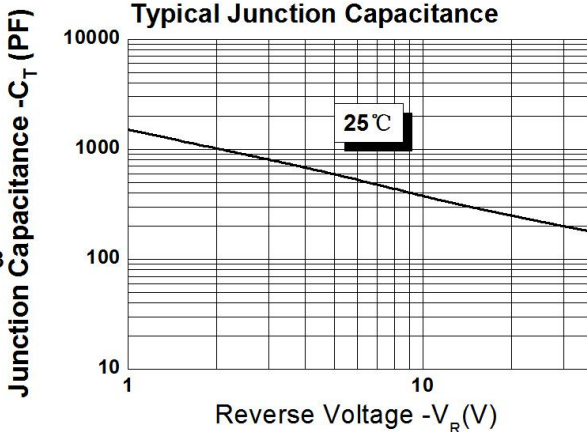


Figure 4
Typical Junction Capacitance

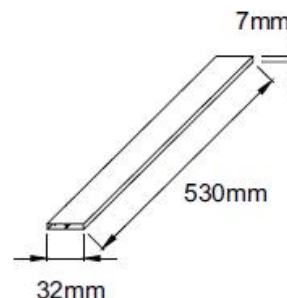


Tube Specification

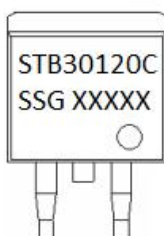
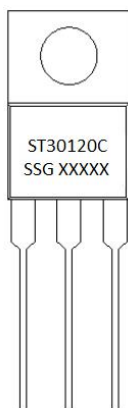
Device	Package	Weight	Shipping
ST30120C	TO-220AB	2.0	50pcs / tube
STB30120C	D ² PAK	1.85	800pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Tube Specification(TO-220AB)



Marking Diagram

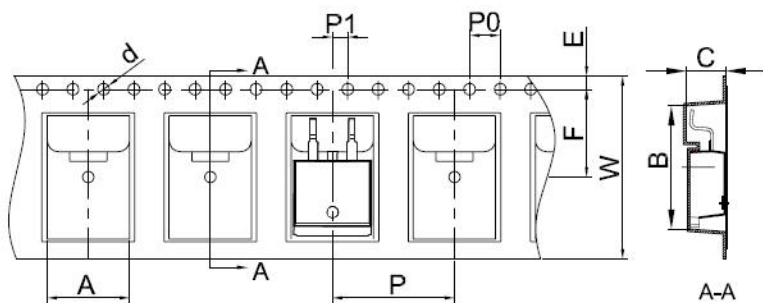


Where XXXXX is YYWWL

ST = Device Type
B = Package type
30 = Forward Current (30A)
120 = Reverse Voltage (120V)
C = Configuration
SSG = SSG
YY = Year
WW = Week
L = Lot Number

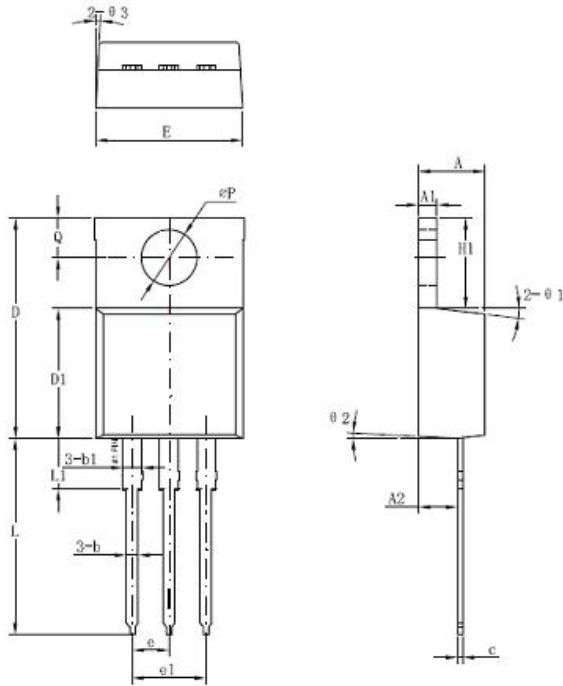
Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification D2PAK



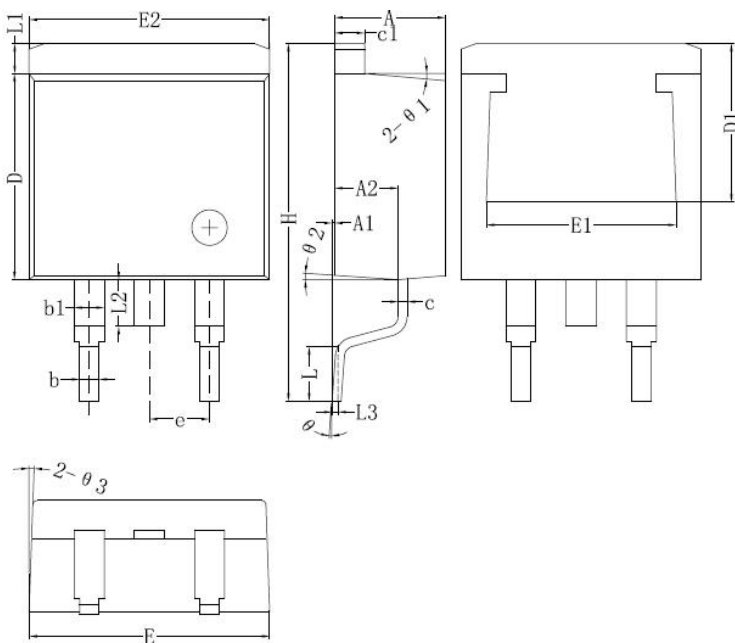
SYMBOL	Millimeters	
	Min.	Max.
A	10.70	10.90
B	16.03	16.23
C	5.11	5.31
d	1.45	1.65
E	1.65	1.85
F	11.40	11.60
P0	3.90	4.10
P	15.90	16.10
P1	1.90	2.10
W	23.90	24.30

Mechanical Dimensions TO-220AB



Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.52	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
e		2.54	
e1	4.98	5.06	5.18
H1	6.04	6.24	6.44
L	12.7	13.56	13.80
L1	3.56	3.5	3.96
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
$\theta 1$		7°	
$\theta 2$		3°	
$\theta 3$		4°	

Mechanical Dimensions D²PAK



Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.47	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
c1	1.17	1.27	1.37
D	8.50	8.70	8.90
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.31
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	1.30		2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

Technical Data
Data Sheet N1369, Rev. A



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